

<b>Patent title:</b>	<b>Method for the construction of a low reflectance semiconductor substrate</b> <b>(Metodo per la realizzazione di un substrato semiconduttore a bassa riflettanza)</b>
<b>FBK center:</b>	CMM
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<b>Application number(s):</b>	IT Patent Application No. 102018000007082 — priority date 2018-07-10
<b>Bibliographic data:</b>	—
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<b>IP status:</b>	Patent pending. Available for license or assignment
<b>Patent family:</b>	—
<b>Application(s):</b>	Generation of black silicon and other high surface/volume ratio surfaces
<b>Keyword(s):</b>	Low reflectance semiconductor substrate, Silicon anisotropic etching, High surface/volume ratio
<b>Abstract:</b>	The present invention concerns a method to obtain black silicon by means of resputtering of mask composites during anisotropic etching. Black silicon consists of thin vertical structures (grass) that can be generated by deep reactive ion etching (DRIE) of a silicon substrate. The structures formation depends on micromasking, which is highly dependent on etching condition fluctuations, making it hard to reproduce the same feature. Scope of the proposed method is to provide a reliable and highly reproducible process for the generation of black silicon in silicon anisotropic etching, based on control of micromasking.